



NOTES:

1. MATERIAL:

1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,
UL94V-0.

1.2 CONTACT: COPPER ALLOY

1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

2.1 CONTACT: 50~100u" NICKEL UNDERPLATING OVERALL.

1: GOLD FLASH.

N: 100~200u" MATT TIN PLATING ON SOLDER TAILS.

L: 100~200u" PURE TIN PLATING.

C: 15U" GOLD ON CONTACT

M: 3U" GOLD ON CONTACT

2.2 FITTING NAIL: 50~100u" NICKEL UNDERPLATING OVERALL.

1: GOLD FLASH.

N: 100~200u" MATT TIN PLATING ON SOLDER TAILS.

L: 100~200u" PURE TIN PLATING.

C: GOLD FLASH.

3. REFLOW SOLDER CAPABLE TO 260°C

PER ACES SPEC.

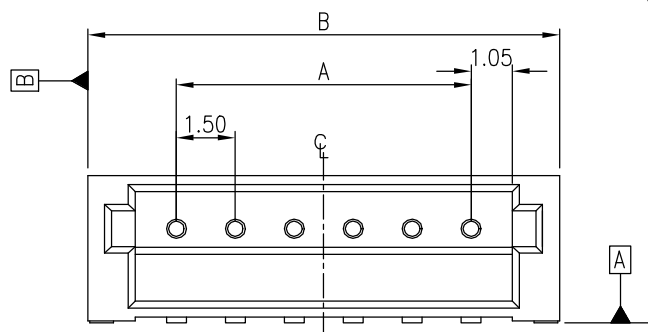
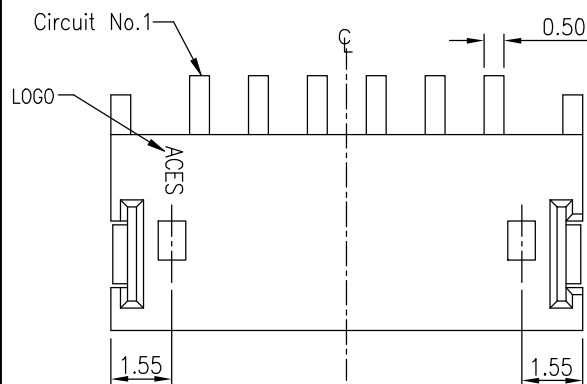
4. SPEC. PLS. REFER TO PS-50287-XXXX-XXX

5. PACKAGE :SEE P/N LEGEND

6. COPLANARITY 0.1MM MAX. BASE ON DATUM A

7. TRUE POSITION 0.1MM MAX. BASE ON DATUM B

8. PART NUMBER



P/N LEGEND

50287-XXX X X-XXX

NO OF CKTS

PACKING

0: TAPE & REEL
1: TUBE PACKAGE

PLATING

L: LEAD FREE

1: GOLD FLASH

N: MATT TIN (LEAD FREE)

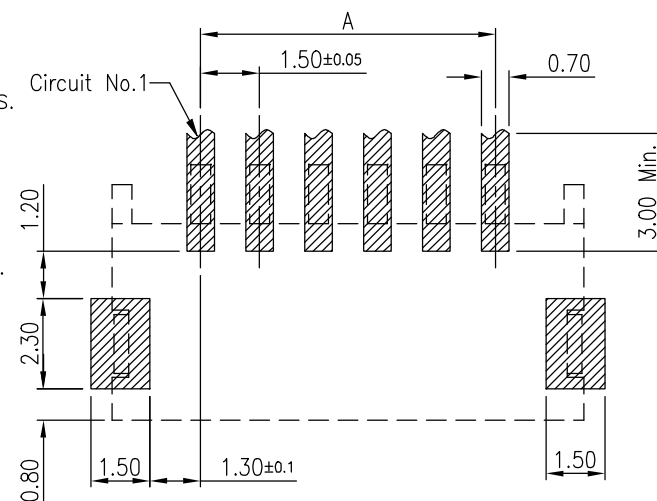
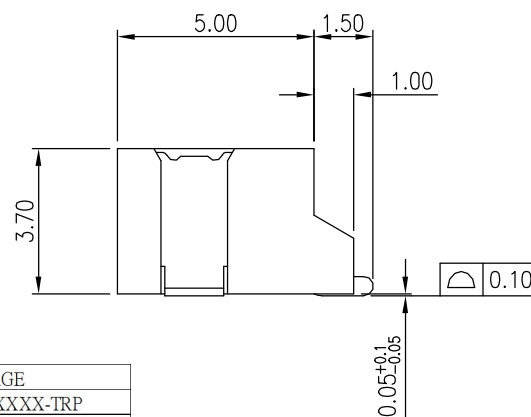
C: CONTACT AREA: 15U" GOLD PLATING

SOLDER AREA: GOLD FLASH

M: CONTACT AREA: 3U" GOLD PLATING





SOLDER AREA: GOLD FLASH

XXX	Material	Color	PACKAGE
001	HF PLASTIC	Black	88260-XXXX-TRP
002	HF PLASTIC	NATURAL	88260-XXXX-TRP
003	HF PLASTIC	NATURAL	88260-XXXX-06-TRP
W01	HF PLASTIC	Black	88260-XXXX-XX-TRP
DM1	HF PLASTIC	Black	88260-XXXX-TRP



PCB PATTERN LAYOUT

CKT	Dim A	Dim B
2	1.5	6.0
3	3.0	7.5
4	4.5	9.0
5	6.0	10.5
6	7.5	12.0
7	9.0	13.5
8	10.5	15.0
9	12.0	16.5
10	13.5	18.0
11	15.0	19.5
12	16.5	21.0
13	18.0	22.5
14	19.5	24.0
15	21.0	25.5

QUALITY SYMBOLS MAJOR  CRITICAL 	DRAWN BY Ding,shuqin		DATE 21/10/08					
	CHECKED BY Lu,Jing Quan		DATE 21/10/08					
	GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°		APPROVED BY hsieh,fu yu		DATE 21/10/08		TITLE 1.5mm Pitch WTB Wafer SMT R/A S/R TYPE	
	UNITS mm				SIZE A4		RFQ NO.	X
SCALE 8 : 1		SHEET NO. 1 OF 1		REV H		PART NO.	SEE NOTES	
						DWG NO.	50287-XXXX-XXX	